

■ **Notice (Rating)**

Do not use products beyond the rated current and rated voltage as this may create excessive heat and deteriorate the insulation resistance.

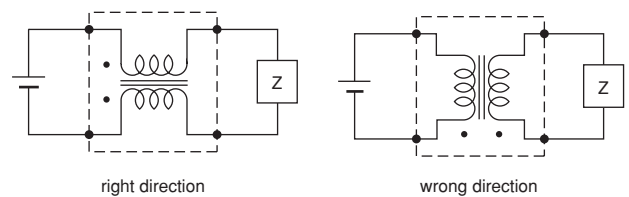
■ **Notice (Soldering and Mounting)**

1. Self-heating

Please provide special attention when mounting chip Micro Chip Transformer (DXP, DXW) series in close proximity to other products that radiate heat. The heat generated by other products may deteriorate the insulation resistance and cause excessive heat in this component.

2. Mounting Direction

Mount Micro Chip Transformer in right direction. Wrong direction, which is 90 degree rotated from right direction, the characteristics does not come out as Micro Chip Transformer or causes not only open or short circuit but also flames or other serious trouble.



■ **Notice (Storage and Operating Conditions, Handling)**

<Operating Environment>

Do not use products in a chemical atmosphere such as chlorine gas, acid or sulfide gas.

<Storage and Handling Requirements>

1. Storage Period

DXP/DXW series should be used within 12 months. Solderability should be checked if this period is exceeded.

2. Storage Conditions

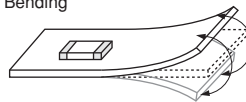
- (1) Storage temperature: -10 to +40 degree C
- Relative humidity: 15 to 85%
- Avoid sudden changes in temperature and humidity.

- (2) Do not store products in a chemical atmosphere such as chlorine gas, acid or sulfide gas.

3. Handling of a Substrate

After mounting products on a substrate, do not apply any stress to the product caused by bending or twisting to the substrate when cropping the substrate, inserting and removing a connector from the substrate or tightening screw to the substrate. Excessive mechanical stress may cause cracking in the Product.

Bending



Twisting

